

ABSTRACT OF THE DISCLOSURE

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A system that decapsulates an integrated circuit
package while the package is mounted to a printed
circuit board. The system includes a tray that
supports a printed circuit board which has at least one
integrated circuit package mounted to the board.
Mounted to the tray is a clamp which clamps an
injection head to the top of the package. The
injection head is coupled to a source of decapsulation
fluid which is sprayed onto the package. The
decapsulation fluid is circulated across the package to
remove the package material and expose the underlying
integrated circuit. The injection head has a gasket
that is pressed onto the package to prevent the fluid
from leaking onto the printed circuit board. After the
plastic is decapsulated the head can be removed from
the package so that the integrated circuit can be
tested while the circuit is connected to the printed
circuit board.